

Amendment and Response

Applicant: Wolfgang Hetzel et al.

Serial No.: 10/577,173

Filed: October 27, 2009

Docket No.: I441.141.101/QIM4346

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND,
SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING SAME

SPECIFICATION

Please amend the paragraph beginning on line 29 of page 11 as follows:

The width b of the metal layer 13 is dimensioned in such a way that it is possible for a number of semiconductor devices 10 to be reliably divided from a panel along sawing tracks without an adhesive layer 11 being able to soil the dividing tool. The gold coating ensures that the adhesion of the plastic package molding compound 2 is reduced in the boundary layer between the material of the plastic package molding compound 2 and the gold coating, so that, in addition to the purely ductile compliance of the gold and copper layers 14, 15 of the metal layer 13, under extreme loading microgaps 17 can also form in the boundary layer, on the one hand permitting a moisture path via which moisture can escape from the semiconductor device 10, whereby the moisture test is improved, and on the other hand permitting compliance in the peripheral region, whereby improved reliability in thermal cycling tests is achieved.